

ABSTRACT***Method for transferring a layer from a source substrate to a destination substrate***

The present description concerns a method of transferring a layer (15) from a source substrate (13) to a destination substrate (17), comprising the following steps:

a) activating a bonding surface of said layer (15) and a bonding surface of the destination substrate (17), by ion etching of said surfaces, or by sputtering of a bonding material onto said surfaces; and

b) after step a), placing into contact the bonding surface of said layer (15) with the bonding surface of the destination substrate (17),

wherein, during step a), a masking ring (21) covers a peripheral portion of the bonding surface of said layer (15), and/or a masking ring (23) covers a peripheral portion of the bonding surface of the destination substrate; and

wherein steps a) and b) are carried out under vacuum and with no rupture of vacuum between the two steps.

(Fig. 1B)